1 Scope

1.1 Contents

This specification covers the requirements for mount of 0.6 mm Pitch Board-to-Board Connector Free Height Type.

114-5255

Application Specification

FH 0.6 Pitch Board-to-Board Connector

(Surface-Mount Technology)

2 Related Specifications

108-5468 Product Specification

501-5164 Test Report

3 Product Features

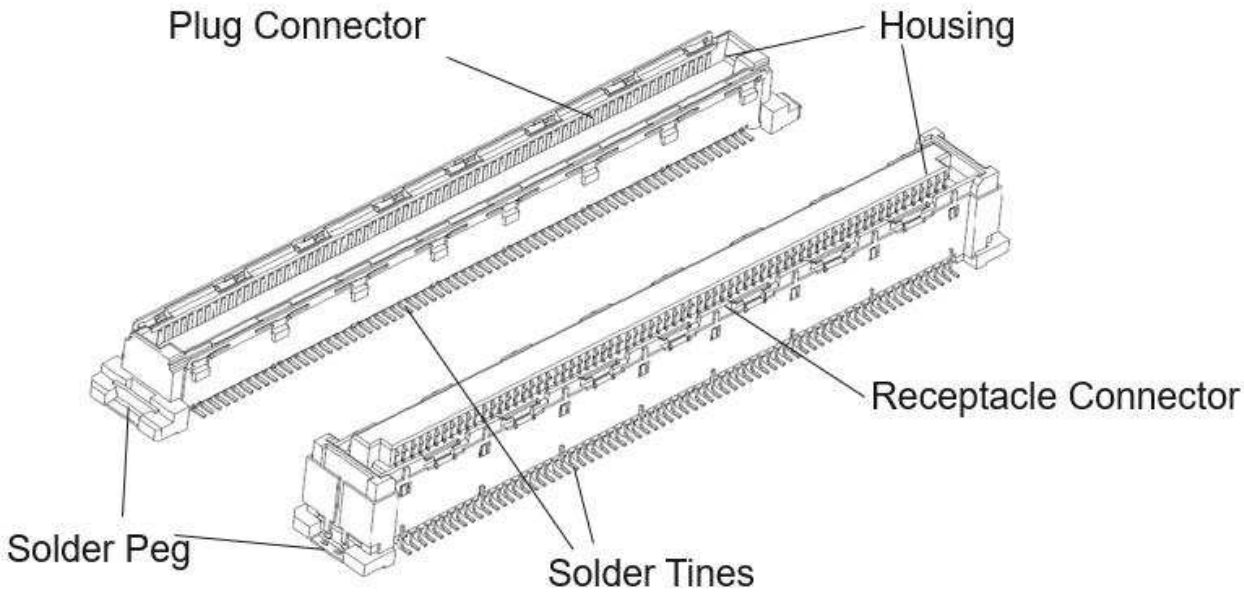

Figure 1

4 Requirements

4.1 Storage

A. This connector is packaged and shipped in an emboss tape, tube or hard tray. We recommend that the connector remain in the container to prevent contamination or dust, that it is stored, keeping at normal temperatures, normal humidity and no poisonous gas.

(Normal temperatures and humidity: 5~35 °C, 45~75% RH)

B. If this connector is stored in the middle of operating, it should not remain naked.

C. We recommend that this connector isn't stored for a long time after opening a package and that it is used within three months.

4.2 Printed Circuit Board

The PC board shall be glass epoxy. If you use a thin board, we recommend you to give support to it from reverse side in order to prevent a bow of board when mating

4.3 PC Board Layout

Please refer to customer drawing.

4.4 Solder Techniques

A. Recommend Solder Paste

1. Alloy type shall be either 63 Sn/37 Pb or 60 Sn/40 Pb.

2. Flux shall be RMA type.

B. Stencil

1. The recommended thickness of stencil: 0.15~0.18mm.

2. Recommended solder volume and an example of aperture pad DIM. (per pad)

	Height (mm)	Solder volume (mm^3)	An example of aperture pad DIM.(mm)	
			Mask thickness: 0.15t	Mask thickness: 0.18t
Plug contact	4	0.088	0.25W x 2.35L	0.25W x 1.96L
	5~12	0.045	0.25W x 1.19L	0.18W x 0.99L
Receptacle contact	5	0.049	0.25W x 1.31L	0.25W x 1.09L
	8.12	0.044	0.25W x 1.16L	0.25W x 0.97L
Solder peg		0.584	3.2W x 1.22L	3.2W x 1.01L

C. Reflow Condition

Preheat: 100~150℃ 60 Sec. Min

Heat: 210℃ Min 30 Sec. Max

Heat peak: 240℃ Max

D. Connector placement

Please adjust the automatic mounter in such a way that it is set up as a surface level,

keeping without deformation of the solder tine. Optimally, the connector solder tine should be aligned as centered on the PC board pads

E. Repair

If a soldering iron is used, full care must be taken not to contact the solder tine by tip of a solder tine by tip of a soldering iron.

Recommended temperature of soldering iron: 300℃ Max

Operating time: 3 Sec. Max. per pad.

4.6 Mating and Un-mating angle (for mechanical installation)

Please do the mating or un-mating work within 2.6°